IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRI	© Copyright 2005. IPC,	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both nternational and Pan-American copyright conventions.			This clevel	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
upplier Inform	nation														
Company name*			Company unique ID			Uni	Unique ID Authority					Response Date*			
nsemi											2025-09-18				
Contact Name		Title - Contact			Pho	Phone - Contact*				Email - Contact*					
Product-Env-Stew	ards	Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com					
uthorized Repres	entative*	Title - Representative			Pho	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Reques	ter Item Number	Number Mfr Item Name			Ef	ffective Dat	te Version	ı	Manufacturing Site		Weight*	UOM	Unit Type		
		NCL30288BSNT1G High PF PWM pri targeting flyback & LED drivers		mary side controller t non-isolated buck-l	boost 20)25-09-18			MY1		14.2	mg	Each		
Ianufacturing	Process Information	n													
Termina	Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSL F		ng	Peak Process Body Temperature Max Time at		ure Max Time at Peak	eak Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU			CU Alloy 3				260 C 30			seconds 3					
omments															
TTENTION: MS	L 3 Rated item requires Ba	ke and D	ry Pack (after	electrical test)											
or more informat	ion regarding material con	nposition p	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.42	mg	Supplier	Silicon (Si)	7440-21-3		0.42	mg
Die Attach	0.07	mg		Epoxy resin	proprietary data		0.021	mg
			Supplier	Fatty acids, C18-unsatd., dimers, polymers with epichlorhydrin	68475-94-5		0.021	mg
			Supplier	2,2'-[[2-(oxiranylmethoxy)-1,3-phenylene]bis(methylene)]bisoxirane	13561-08-5		0.021	mg
			Supplier	4-Methyl-2-Phenyl-1H-Imidazole	827-43-0		0.0063	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0007	mg
Lead Frame	5.84	mg	Supplier	Silver (Ag)	7440-22-4		0.0712	mg
			Supplier	Zinc (Zn)	7440-66-6		0.007	mg
			Supplier	Iron (Fe)	7439-89-6		0.1372	mg
			Supplier	Copper (Cu)	7440-50-8		5.6228	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0018	mg
Mold Compound-Black	7.33	mg		Epoxy resin	proprietary data		0.3665	mg
			Supplier	Phenolic Resin	Proprietary Data		0.3665	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1466	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0366	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4137	mg
Plating	0.47	mg	Supplier	Tin (Sn)	7440-31-5		0.47	mg
Wire Bond - Au	0.07	mg	Supplier	Gold (Au)	7440-57-5		0.07	mg